



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN#20150909000A

**Qualification of Hana Thailand as an Additional Assembly & Test site for select
devices in the DQN package
Change Notification / Sample Request**

Date: 10/30/2015
To: MOUSER PCN

Dear Customer:

Revision A is to announce the addition of new devices that were not included on the original PCN notification.

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The changes discussed within this PCN will not take effect any earlier than **90** days from the date of this notification, unless customer agreement has been reached on an earlier implementation of the change. This notification period is per TI's standard process.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services

20150909000A
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
LP5907SNX-2.9/NOPB	null
LP5907SNX-4.0/NOPB	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20150909000A			PCN Date:	10/30/2015						
Title:	Qualification of Hana Thailand as an Additional Assembly & Test site for select devices in the DQN package										
Customer Contact:	PCN Manager		Dept:	Quality Services							
Proposed 1st Ship Date:	01/30/2016		Estimated Sample Availability:	Provided upon Request							
Change Type:											
☒	Assembly Site	☐	Assembly Process	☒	Assembly Materials						
☐	Design	☐	Electrical Specification	☐	Mechanical Specification						
☒	Test Site	☐	Packing/Shipping/Labeling	☐	Test Process						
☐	Wafer Bump Site	☐	Wafer Bump Material	☐	Wafer Bump Process						
☐	Wafer Fab Site	☐	Wafer Fab Materials	☐	Wafer Fab Process						
	☐	Part number change									
PCN Details											
Description of Change:											
Revision A is to announce the addition of new devices that were not included on the original PCN notification. These new devices are highlighted and bolded in the device list below. The expected first shipment date for these new devices will be 90 days from this notice for these newly added devices only. Texas Instruments is pleased to announce the qualification of Hana Thailand as an additional Assembly & Test site for select devices in the DQN package shown in the table below. BOM differences are noted below: <table border="1" style="margin-left: auto; margin-right: auto;"> <tr> <td></td> <td style="text-align: center;">JCET</td> <td style="text-align: center;">HNT</td> </tr> <tr> <td>Mount Compound</td> <td style="text-align: center;">S#120402001600</td> <td style="text-align: center;">SID#400173</td> </tr> </table> Test coverage, insertions, conditions will remain consistent with current testing and verified with test MQ.							JCET	HNT	Mount Compound	S#120402001600	SID#400173
	JCET	HNT									
Mount Compound	S#120402001600	SID#400173									
Reason for Change:											
Continuity of Supply											
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):											
None											
Anticipated impact on Material Declaration											
☐	No Impact to the Material Declaration	☒	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained from the TI ECO website .								
Changes to product identification resulting from this PCN:											
Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (21L)	Assembly City								
JCET	JCE	CHN	Jiangyin								
HNT	HNN	THA	Ayutthaya								
Sample product shipping label (not actual product label)											



MADE IN: Malaysia
2DC: 2Q:

MSL 2 /260C/1 YEAR	SEAL DT
MSL 1 /235C/UNLIM	03/29/04

OPT:
ITEM:

LBL: 5A (L)T0:1750



(1P) SN74LS07NSR

(Q) 2000 (D) 0336

(31T) LOT: 3959047MLA

(4W) TKY (1T) 7523483SI2

(P)

(2P) REV: (V) 0033317

(20L) CS0: SHE (21L) CC0: USA

(22L) AS0: MLA (23L) ACO: MYS

Topside Device marking:

Assembly site code for JCET= F

Assembly site code for HNT = H

Product Affected

LP5907SNX-1.2/NOPB	LP5907SNX-2.7/NOPB	LP5907SNX-3.0/NOPB	LP5907SNX-4.0/NOPB
LP5907SNX-1.8/NOPB	LP5907SNX-2.8/NOPB	LP5907SNX-3.1/NOPB	LP5907SNX-4.5/NOPB
LP5907SNX-2.2/NOPB	LP5907SNX-2.85/NOPB	LP5907SNX-3.2/NOPB	
LP5907SNX-2.5/NOPB	LP5907SNX-2.9/NOPB	LP5907SNX-3.3/NOPB	



TI Information
Selective Disclosure

Qualification Report

Hana - Thailand as 2nd Site Multi-Source for LP5907SNX Family Cat2CF Qualification

Approved 07/31/2015

Product Attributes

Attributes	Qual Device: LP5907SNX-2.85/ NOPB	QBS Package Reference: TLV70750DQN	QBS Package Reference: TLV70750DQN
Assembly Site	HANA - THAILAND	HANA -THAILAND	HANA - THAILAND
Package Family	X2SON	X2SON	X2SON
Flammability Rating	UL 94 V-0	UL 94 V-0	UL 94 V-0
Wafer Fab Site	AIZU	MIHO8	MIHO8
Wafer Fab Process	CMOS9T	LBC7	LBC7

- QBS: Qual By Similarity

- Qual Device LP5907SNX-2.84/NOPB is qualified at MSL1

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed



Type	Test Name / Condition	Duration	Qual Device: LP5907 SNX- 2.85/NOPB	QBS Package Reference: TLV70750DQN	QBS Package Reference: TLV70750DQN
PC	PreCon Level 1	ATE	1/231/0	1/305/0	3/847/0
HAST	Biased HAST, 130C/85%RH	96 Hours	1/77/0	1/77/0	3/231/0
THB	Biased Temperature and Humidity, 85C/85%RH	1000 Hours	-	-	-
AC	Autoclave 121C	96 Hours	-	1/77/0	-
UHAST	Unbiased HAST 110C/85%RH	96 Hours	1/77/0	1/77/0	2/154/0
TC	Temperature Cycle, -65/150C	500 Cycles	1/77/0	1/77/0	3/231/0
HTSL	High Temp Storage Bake 150C	1000 Hours	1/45/0	-	-
HTSL	High Temp Storage Bake 170C	420 Hours	-	1/77/0	3/231/0
HTOL	Life Test, 125C	1000 Hours	1/77/0	-	-
ELFR	Early Life Failure Rate, 125C	48 Hours	-	-	-
WBS	Ball Bond Shear	5 units, >76 balls, 0 fails	3/60/0	1/76/0	1/76/0
WBP	Bond Pull	4 Wire, 5 units min	3/60/0	-	2/152/0
SD	Solderability	Steam age, 8 Hours	3/60/0	1/22/0	2/44/0
PD	Physical Dimensions	(per mechanical drawing)	3/60/0	1/5/0	2/10/0
HBM	ESD - HBM	2000 V	1/3/0	1/3/0	1/3/0
CDM	ESD - CDM	1000 V	1/3/0	1/3/0	-
LU	Latch-up	(per JESD78)	1/6/0	1/6/0	-
ED	Electrical Characterization	Over Temperature	1/30/0	1/30/0	-
DS	Die Shear	-	-	1/15/0	1/10/0
MECH	Visual / Mechanical	-	-	1/459/0	-
MQ	Manufacturability	(per mfg. Site specification)	3/Pass	1/Pass	-
MSL	Moisture Sensitivity, L1 260C	3 Cycles / 260 C	-	-	-
XRAY	X-ray	(top side only)	-	-	-

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com